## **Power MOSFET**

## 40 V, 4.2 m $\Omega$ , 120 A, Single N-Channel

#### **Features**

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Q<sub>G</sub> and Capacitance to Minimize Driver Losses
- NVMFS5832NLWF Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	40	V
Gate-to-Source Voltage	Gate-to-Source Voltage			± 20	V
Continuous Drain Current R <sub>Ψ,I-mb</sub> (Notes 1,	Steady	T <sub>mb</sub> = 25°C	I <sub>D</sub>	120	Α
2, 3, 4)		T <sub>mb</sub> = 100°C		84	
Power Dissipation	State	T <sub>mb</sub> = 25°C	$P_{D}$	127	W
R <sub>ΨJ-mb</sub> (Notes 1, 2, 3)		T <sub>mb</sub> = 100°C		64	
Continuous Drain Cur-		T <sub>A</sub> = 25°C	I <sub>D</sub>	21	Α
rent R <sub>θJA</sub> (Notes 1, 3, 4)	Steady	T <sub>A</sub> = 100°C		15	
Power Dissipation	State	T <sub>A</sub> = 25°C	$P_{D}$	3.7	W
R <sub>0JA</sub> (Notes 1 & 3)		T <sub>A</sub> = 100°C		1.9	
Pulsed Drain Current	T <sub>A</sub> = 25	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	557	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	–55 to + 175	°C
Source Current (Body Diode)			I <sub>S</sub>	120	Α
Single Pulse Drain-to-Source Avalanche Energy (T <sub>J</sub> = 25°C, V <sub>GS</sub> = 10 V, I <sub>L(pk)</sub> = 52 A, L = 0.1 mH, R <sub>G</sub> = 25 $\Omega$ )			E <sub>AS</sub>	134	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Mounting Board (top) - Steady State (Notes 2, 3)	$R_{\Psi J-mb}$	1.2	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	40	

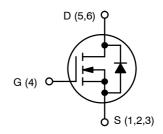
- 1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Psi  $(\Psi)$  is used as required per JESD51-12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.
- Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.



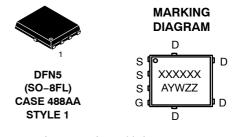
#### ON Semiconductor®

#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX	
40 V	4.2 mΩ @ 10 V	100 4	
40 V	6.5 mΩ @ 4.5 V	120 A	



**N-CHANNEL MOSFET** 



A = Assembly Location

Y = Year W = Work Week ZZ = Lot Traceability

#### **ORDERING INFORMATION**

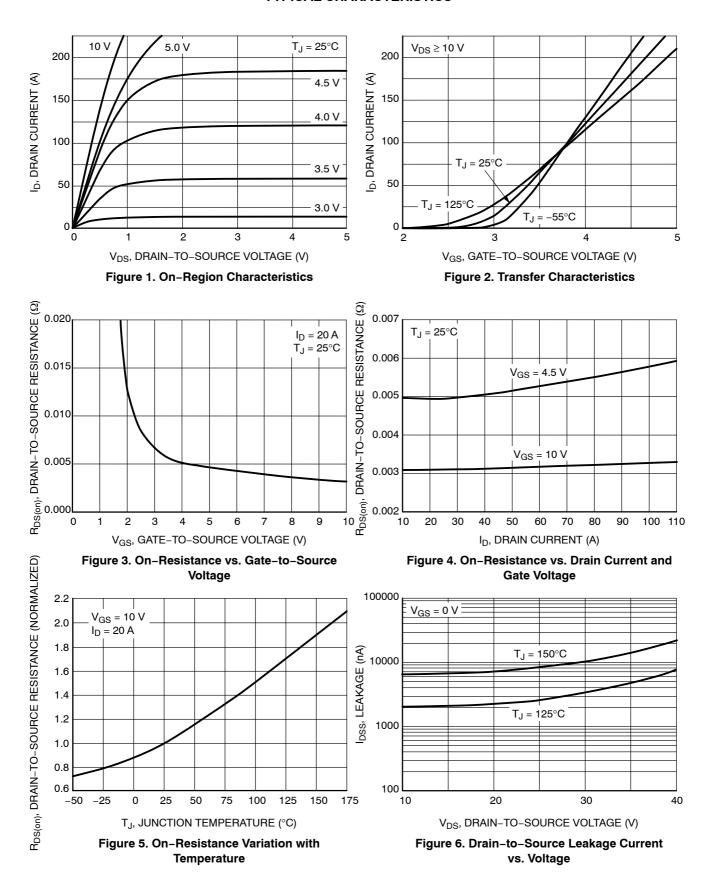
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condi	tion	Min	Тур	Max	Unit
OFF CHARACTERISTICS						1	•
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /				34.2		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V$ ,	T <sub>J</sub> = 25 °C			1	
		V <sub>DS</sub> = 40 V	T <sub>J</sub> = 125°C			100	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$				±100	nA
ON CHARACTERISTICS (Note 5)					•	•	•
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D =$	= 250 μΑ	1.4		2.4	V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				6.4		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 20 A		3.1	4.2	_
		V <sub>GS</sub> = 4.5 V	I <sub>D</sub> = 20 A		5.0	6.5	mΩ
Forward Transconductance	9FS	V <sub>DS</sub> = 15 V, I <sub>D</sub>	= 20 A		21		S
CHARGES, CAPACITANCES & GATE RESIS	TANCE				•	•	•
Input Capacitance	C <sub>ISS</sub>				2700		
Output Capacitance	C <sub>OSS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 25 V			360		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>				250		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 20 A			25		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 20 A			51		1
Threshold Gate Charge	Q <sub>G(TH)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 20 V; I <sub>D</sub> = 20 A			2.0		nC
Gate-to-Source Charge	Q <sub>GS</sub>				8.0		
Gate-to-Drain Charge	Q <sub>GD</sub>				12.7		
Plateau Voltage	V <sub>GP</sub>				3.2		V
SWITCHING CHARACTERISTICS (Note 6)					•		•
Turn-On Delay Time	t <sub>d(ON)</sub>				13		
Rise Time	t <sub>r</sub>	$V_{GS} = 4.5 \text{ V}, V_{DS}$	s = 20 V.		24		1
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$I_D = 10 \text{ A}, R_G = 1.0 \Omega$			27		ns
Fall Time	t <sub>f</sub>				8.0		
DRAIN-SOURCE DIODE CHARACTERISTIC	s					1	
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C		0.73	1.2	
		$I_S = 5 A$	T <sub>J</sub> = 125°C		0.57		V
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, dIS/dt} = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 10 \text{ A}$			28.6		
Charge Time	ta				14		ns
Discharge Time	t <sub>b</sub>				14.5		1
Reverse Recovery Charge	Q <sub>RR</sub>				23.4		nC

<sup>5.</sup> Pulse Test: pulse width  $\leq 300~\mu s$ , duty cycle  $\leq 2\%$ .
6. Switching characteristics are independent of operating junction temperatures.

#### TYPICAL CHARACTERISTICS



#### TYPICAL CHARACTERISTICS

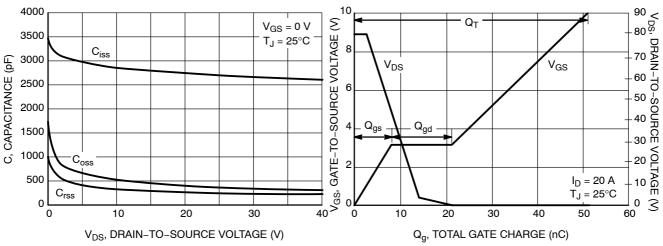


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Charge

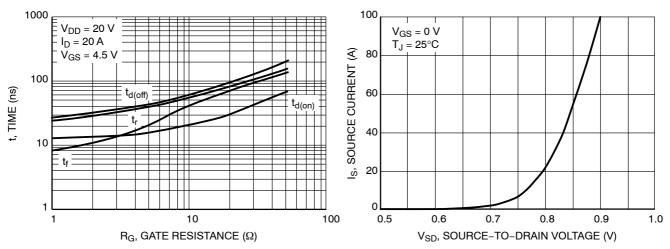


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

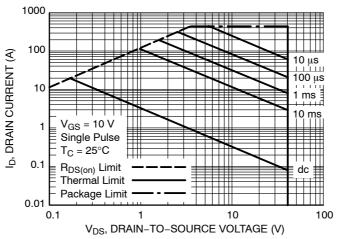


Figure 11. Maximum Rated Forward Biased Safe Operating Area

#### **TYPICAL CHARACTERISTICS**

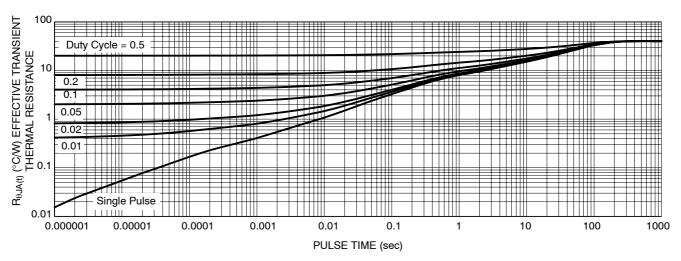


Figure 12. Thermal Response

#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NVMFS5832NLT1G	V5832L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5832NLWFT1G	5832LW	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5832NLT3G	V5832L	DFN5 (Pb-Free)	5000 / Tape & Reel
NVMFS5832NLWFT3G	5832LW	DFN5 (Pb-Free)	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



0.10

0.10

SIDE VIEW

**DFN5 5x6, 1.27P (SO-8FL)** CASE 488AA ISSUE N

**DATE 25 JUN 2018** 

#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е		1.27 BSC		
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
M	3.00	3.40	3.80	
θ	0 °		12 °	

# GENERIC MARKING DIAGRAM\*

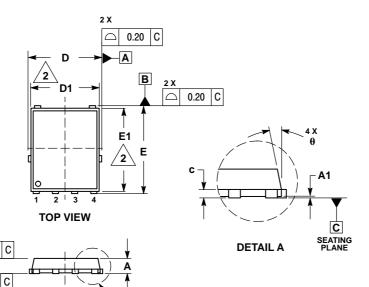


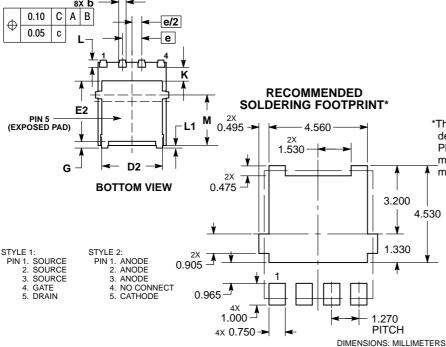
XXXXXX = Specific Device Code

A = Assembly Location Y = Year

W = Work Week
ZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " •", \_may or may not be present. Some products may not follow the Generic Marking.





**DETAIL A** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER: 98AON14036D Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.

DESCRIPTION: DFN5 5x6, 1.27P (SO-8FL) PAGE 1 OF 1

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, Onsemi, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase

#### **PUBLICATION ORDERING INFORMATION**

LITERATURE FULFILLMENT:
Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by ON Semiconductor manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 FCA20N60\_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D TPCC8103,L1Q(CM MIC4420CM-TR VN1206L SBVS138LT1G 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C BUK954R8-60E NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE222 NTE2384 NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956 NTE2956 NTE2911 DMN2080UCB4-7 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B